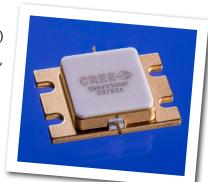


CGHV31500F

500 W, 2700 - 3100 MHz, 50-Ohm Input/Output Matched, GaN HEMT for S-Band Radar Systems

Cree's CGHV31500F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically with high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV31500F ideal for 2.7 - 3.1 GHz S-Band radar amplifier applications. The transistor is supplied in a ceramic/metal flange package, type 440217.



PN: CGHV31500F Package Type: 440217

Typical Performance Over 2.7-3.1 GHz (T_c = 25°C) of Demonstration Amplifier

Parameter	2.7 GHz	2.9 GHz	3.1 GHz	Units
Output Power	665	705	645	W
Gain	13.2	13.5	13.1	dB
Drain Efficiency	66	68	62	%

Note:

Measured in the CGHV31500F-AMP application circuit, under 500 μ s pulse width, 10% duty cycle, P_{IN} = 45 dBm.

Features

- 2.7 3.1 GHz Operation
- 675 W Typical Output Power
- 13.3 dB Power Gain
- 66% Typical Drain Efficiency
- 50 Ohm Internally Matched
- <0.3 dB Pulsed Amplitude Droop



Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Pulse Width	PW	500	μs	
Duty Cycle	DC	10	%	
Drain-Source Voltage	V _{DSS}	125	Volts	25°C
Gate-to-Source Voltage	$V_{\sf GS}$	-10, +2	Volts	25°C
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T,	225	°C	
Maximum Forward Gate Current	I _{GMAX}	80	mA	25°C
Maximum Drain Current ¹	I _{DMAX}	24	Α	25°C
Soldering Temperature ²	T _s	245	°C	
Screw Torque	τ	40	in-oz	
Pulsed Thermal Resistance, Junction to Case	$R_{_{\theta JC}}$	0.22	°C/W	100 μsec, 10%, 85°C , P _{DISS} = 376 W
Pulsed Thermal Resistance, Junction to Case	$R_{_{ heta JC}}$	0.30	°C/W	500 μ sec, 10%, 85°C, P_{DISS} = 376 W
Case Operating Temperature	T _c	-40, +85	°C	

Notes:

Electrical Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics ¹ (T _c = 25°C)	DC Characteristics¹(T _c = 25°C)					
Gate Threshold Voltage	V _{GS(th)}	-3.8	-3.0	-2.3	V _{DC}	V _{DS} = 10 V, I _D = 83.6 mA
Gate Quiescent Voltage	$V_{_{GS(\mathtt{Q})}}$	-	-2.7	-	V _{DC}	$V_{DS} = 50 \text{ V, } I_{D} = 0.5 \text{ A}$
Saturated Drain Current ²	I _{DS}	62.7	75.5	-	А	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	$V_{_{\mathrm{BR}}}$	150	-	-	V _{DC}	V _{GS} = -8 V, I _D = 83.6 mA

Notes:

¹ Current limit for long term, reliable operation

² Refer to the Application Note on soldering at http://www.cree.com/rf/document-library

¹ Measured on wafer prior to packaging.

² Scaled from PCM data.



Electrical Characteristics Continued...

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
RF Characteristics ³ (T _c = 25°C, F ₀ = 2.7 - 3.1 GHz unless otherwise noted)							
Output Power at 2.7 GHz	P _{out1}	-	665	-	W	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Output Power at 2.9 GHz	P _{OUT2}	-	705	-	W	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Output Power at 3.1 GHz	P _{out3}	-	645	-	W	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Gain at 2.7 GHz	G _{P1}	-	13.2	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Gain at 2.9 GHz	G _{P2}	-	13.5	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Gain at 3.1 GHz	G_{P3}	-	13.1	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Drain Efficiency at 2.7 GHz	D _{E1}	-	66	-	%	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Drain Efficiency at 2.9 GHz	D _{E2}	-	68	-	%	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Drain Efficiency at 3.1 GHz	D _{E3}	-	62	-	%	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Small Signal Gain	S21	-	14.5	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = -10 \text{ dBm}$	
Input Return Loss	S11	-	-15	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = -10 \text{ dBm}$	
Output Return Loss	S22	-	-6	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = -10 \text{ dBm}$	
Amplitude Droop	D	-	-0.3	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm}$	
Output Stress Match	VSWR	-	5:1	-	Ψ	No damage at all phase angles, $V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA, } P_{IN} = 45 \text{ dBm Pulsed}$	

Notes

 $^{^3}$ Measured in CGHV31500F-AMP. Pulse Width = 500 μS , Duty Cycle = 10%.



Typical Performance

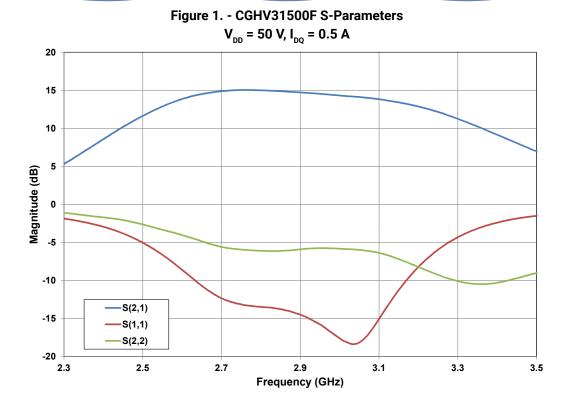
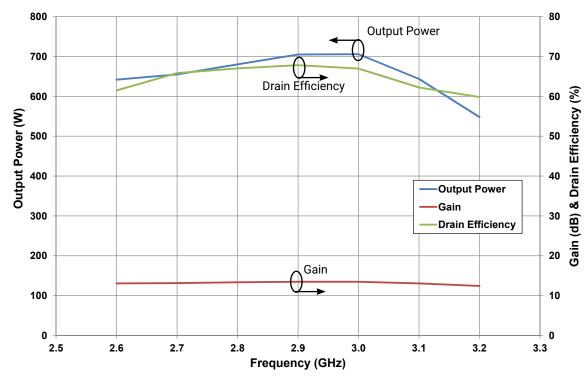


Figure 2. - CGHV31500F Output Power and Drain Efficiency vs Frequency V_{DD} = 50 V, I_{DQ} = 0.5 A, P_{IN} = 45 dBm, Pulse Width = 500 μ s, Duty Cycle = 10%, T_{CASE} = 25°C

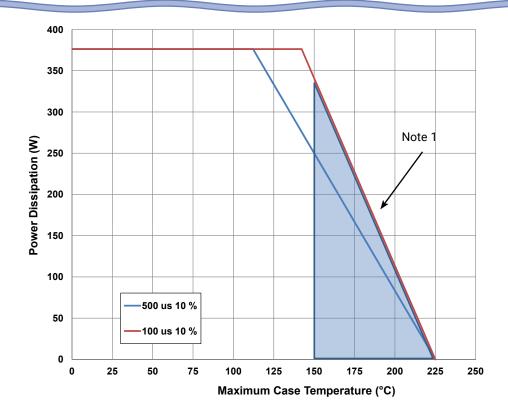




CGHV31500F-AMP Application Circuit Bill of Materials

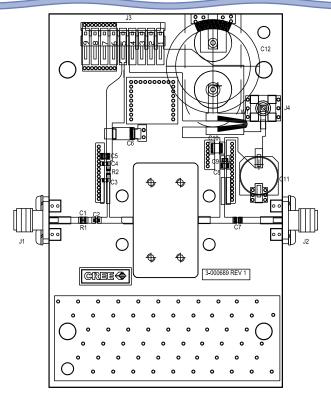
Designator	Description	Qty
R1	RES, 511, OHM, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1, OHM, +/- 1%, 1/16W, 0603	1
C1	CAP, 6.8pF, +/-0.25%, 250V, 0603	1
C2, C7, C8	CAP, 10.0pF, +/-1%, 250V, 0805	3
C3	CAP, 10.0pF, +/-5%, 250V, 0603	1
C4, C9	CAP, 470pF, 5%, 100V, 0603, X	2
C5	CAP, 33000 pF, 0805, 100V, X7R	1
C6	CAP, 10uF 16V TANTALUM	1
C10	CAP, 1.0uF, 100V, 10%, X7R, 1210	1
C11	CAP, 33uF, 20%, G CASE	1
C12	CAP, 3300uF, +/-20%, 100V, ELECTROLYTIC	1
J1,J2	CONN, SMA, PANEL MOUNT JACK, FL	2
J3	HEADER, RT>PLZ, 0.1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
W1	CABLE, 18 AWG, 4.2	1
-	PCB, RO4350, 2.5 X 4.0 X 0.030	1
Q1	CGHV31500F	1

CGHV31500F Power Dissipation De-rating Curve

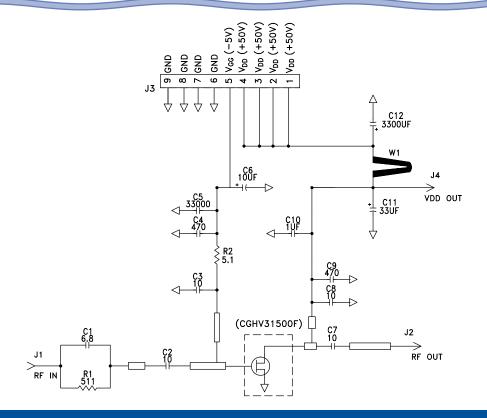




CGHV31500F-AMP Application Circuit Outline



CGHV31500F-AMP Application Circuit Schematic

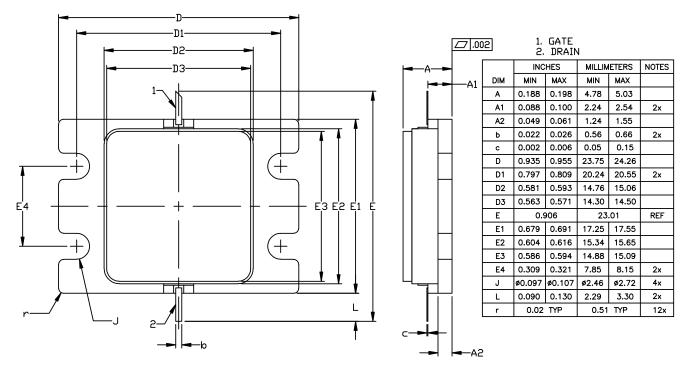




Product Dimensions CGHV31500F (Package Type - 440217)

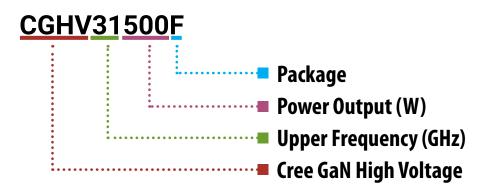
NOTES: (UNLESS OTHERWISE SPECIFIED)

- 1. INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-2009
- 2. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF .020 BEYOND EDGE OF LID
- 3. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF .008 IN ANY DIRECTION
- 4. ALL PLATED SURFACES ARE GOLD OVER NICKEL





Part Number System



Parameter	Value	Units
Upper Frequency ¹	3.1	GHz
Power Output	500	W
Package	Flange	-

Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
А	0
В	1
С	2
D	3
Е	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Table 2.



Product Ordering Information

Order Number	Description	Unit of Measure	lmage
CGHV31500F	GaN HEMT	Each	CRESCOF CORNAGE OF COR
CGHV31500F-TB	Test board without GaN HEMT	Each	
CGHV31500F-AMP	Test board with GaN HEMT installed	Each	



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